

**IV B.Tech I Semester Supplementary Examinations, November 2005**  
**VLSI TECHNOLOGY**  
**(Electronics & Computer Engineering)**

**Time: 3 hours**

**Max Marks: 80**

**Answer any FIVE Questions**  
**All Questions carry equal marks**

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1. (a) Explain why a thin oxide layer is required in MOS fabrication ? [8]  
(b) What is meant by twin tube process and explain where it is used? [8]
2. (a) Explain different types of scaling models. Write down scaling factors used for these models.  
(b) Bring out the effects of scaling on the following parameters in all three models:
  - i. Gate capacitance.
  - ii. Maximum operating frequency.
  - iii. Power speed product. [6+10]
3. (a) What are the different types of programmable inter connection channels used for routing parts in FPGAs? Explain  
(b) Explain about anti fuses used in FPGAs [8+8]
4. (a) Discuss in detail semi-custom layout styles. [8]  
(b) Explain in detail about the configurable logic blocks. [8]
5. Briefly explain the following verification tools: [4x4=16]
  - (a) timing verifiers
  - (b) design rule checkers
  - (c) layout extractions and
  - (d) test vectors.
6. Discuss the following types of simulations. [4+3+3+3+3]
  - (a) circuit level
  - (b) logic level
  - (c) switch level
  - (d) mixed mode and
  - (e) timing simulations
7. (a) What are the various requirements while in designing package?  
(b) What is the difference between through hole and surface mount packages. [8+8]

8. (a) Prove that the combination of BJT and MOS technology offers the best performance in Analog VLSI design.
- (b) Draw the block diagram of D/A converter suitable for VLSI Analog Circuits and explain. [8+8]

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